

ABSTRACT

TITLE OF INVENTION: COMPOSITION FOR FORMING WAFER-EDGE-PROTECTION FILM, WAFER-EDGE-PROTECTION FILM FORMING METHOD, AND PATTERNING PROCESS

The present invention is a composition for forming a wafer-edge-protection film for forming a wafer-edge-protection film on a peripheral edge of a substrate, including a polymer (A) represented by the following general formula (1) and a solvent. In the formula (1), "W" represents $-SO_2-$, $-C(=O)-$, or $-O-$; R_1 , R_2 , R_3 , R_4 , and R_5 each independently represent a halogen atom, a monovalent organic group having 1 to 3 carbon atoms, or a hydroxy group; and "a", "b", "c", "d", and "e" each independently represent an integer of 0 to 4. This can provide a composition for forming a wafer-edge-protection film capable of providing a wafer-edge-protection film that can exhibit excellent dry etching resistance and excellent uniform coatibility, even on a wafer edge that is difficult to be coated.

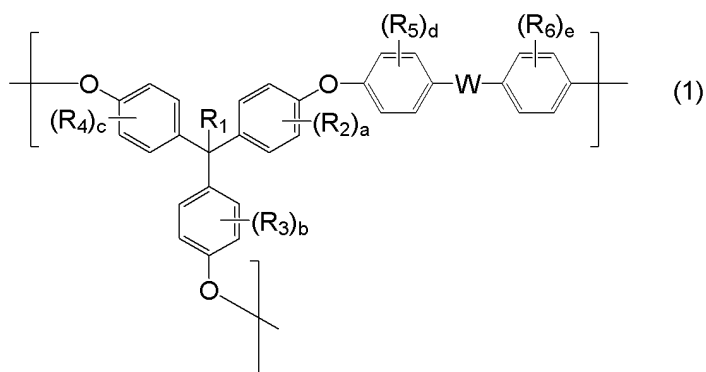


FIG. 2